SMT Power Inductors

Series/Type: B82479G1

The following products presented in this data sheet are being withdrawn.

Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
B82479G1684M000		2020-05-29	2020-11-30	2021-05-31
B82479G1683M000		2020-05-29	2020-11-30	2021-05-31
B82479G1474M000		2020-05-29	2020-11-30	2021-05-31

Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
B82479G1473M000		2020-05-29	2020-11-30	2021-05-31
B82479G1334M000		2020-05-29	2020-11-30	2021-05-31
B82479G1333M000		2020-05-29	2020-11-30	2021-05-31
B82479G1224M000		2020-05-29	2020-11-30	2021-05-31
B82479G1223M000		2020-05-29	2020-11-30	2021-05-31
B82479G1154M000		2020-05-29	2020-11-30	2021-05-31
B82479G1153M000		2020-05-29	2020-11-30	2021-05-31
B82479G1105M000		2020-05-29	2020-11-30	2021-05-31
B82479G1104M000		2020-05-29	2020-11-30	2021-05-31
B82479G1103M000		2020-05-29	2020-11-30	2021-05-31

Please contact your nearest TDK sales office if you need support in selecting a suitable substitute. The addresses of our worldwide sales network are presented at www.tdk-electronics.tdk.com/sales.

SMT power inductors B82479G1

Size 18.5 x 15.24 x 7.25 (mm)

SMD

Rated inductance 10 ... 1000 µH
Rated current 0.53 ... 3.9 A

Construction

- Ferrite core
- Magnetically shielded
- Winding: enamel copper wire
- Winding soldered to terminals
- Plastic terminal carrier

Features

- Temperature range up to +150 °C
- High rated current
- Low DC resistance
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020D
- RoHS-compatible

Applications

- Filtering of supply voltages
- Coupling, decoupling
- DC/DC converters
- Automotive electronics
- Telecommunications
- Industrial electronics

Terminals

- Base material CuSn6P
- Layer composition Ni, Sn (lead-free)
- Electro-plated

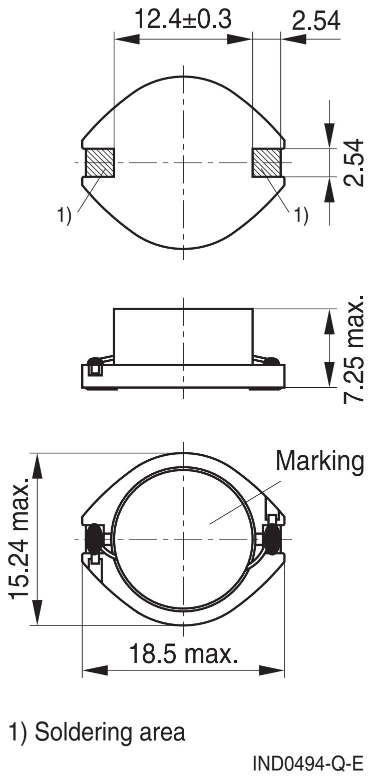
Marking

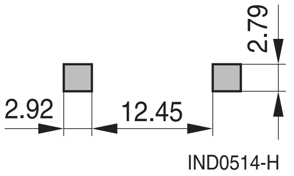
- Marking on component:
  Manufacturer, L value (µH, coded),
  manufacturing date (YWWD)
- Minimum data on reel:
  Manufacturer, ordering code, L value,
  quantity, date of packing

Delivery mode and packing unit

- 32-mm blister tape, wound on 330-mm ∅ reel
- Packing unit: 250 pcs./reel

Dimensional drawing and layout recommendation



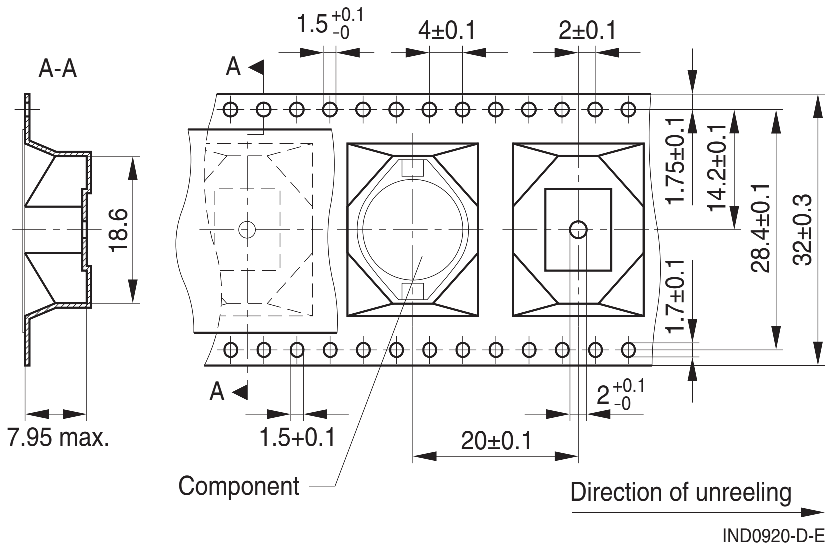


Dimensions in mm

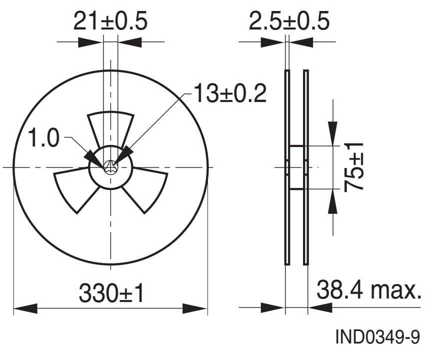
Component tolerances ±0.2 mm unless otherwise noted.

Taping and packing

Blister tape



Reel



Dimensions in mm

Technical data and measuring conditions

Rated inductance L_R	Measured with LCR meter Agilent 4284A at frequency f_L, 0.1 V, +20 °C
Rated temperature T_R	+85 °C
Rated current I_R	Max. permissible DC with temperature increase of ≤ 40 K at rated temperature
Saturation current I_{sat}	Max. permissible DC with inductance decrease $\Delta L/L_0$ of approx. 10%
DC resistance R_{max}	Measured at +20 °C
Solderability (lead-free)	Dip and look method Sn95.5Ag3.8Cu0.7: +(245 ±5) °C, (5 ±0.3) s Wetting of soldering area ≥ 90% (based on IEC 60068-2-58)
Resistance to soldering heat	+260 °C, 40 s (as referenced in JEDEC J-STD 020D)
Climatic category	55/150/56 (to IEC 60068-1)
Storage conditions	Mounted: –55 °C … +150 °C Packaged: –25 °C … +40 °C, ≤ 75% RH
Weight	Approx. 4.2 g

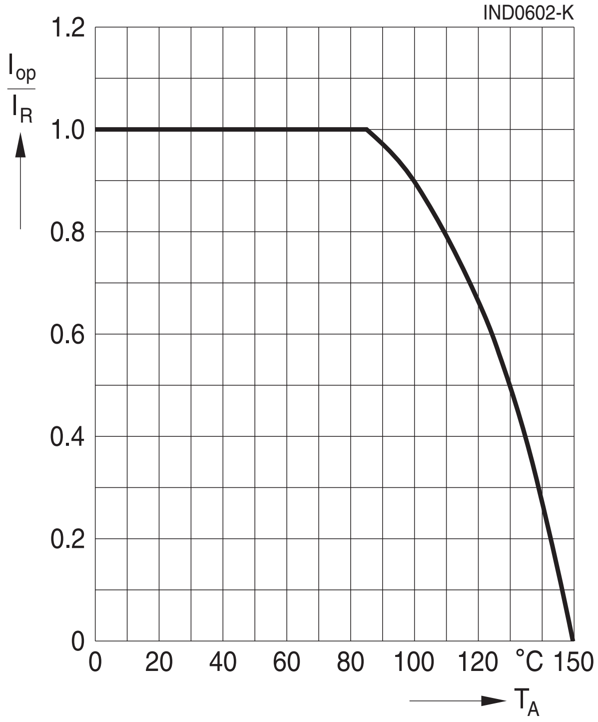
Characteristics and ordering codes

L_R μH	Tolerance	f_L MHz	I_R A	I_{sat} A	R_{max} Ω	Ordering code
10	±20% ≙ M	0.1	3.90	8.00	0.040	B82479G1103M000
15		0.1	3.40	7.00	0.048	B82479G1153M000
22		0.1	3.10	6.00	0.059	B82479G1223M000
33		0.1	2.80	5.00	0.075	B82479G1333M000
47		0.1	2.40	4.00	0.097	B82479G1473M000
68		0.1	2.00	3.00	0.138	B82479G1683M000
100		0.1	1.70	2.40	0.207	B82479G1104M000
150		0.1	1.30	2.10	0.293	B82479G1154M000
220		0.1	1.10	1.90	0.47	B82479G1224M000
330		0.1	0.86	1.20	0.78	B82479G1334M000
470		0.1	0.73	1.10	1.08	B82479G1474M000
680		0.1	0.64	0.96	1.40	B82479G1684M000
1000		0.1	0.53	0.80	2.01	B82479G1105M000

Sample kit available. Ordering code: B8247XX001
For more information refer to chapter “Sample kits”.

Current derating I_{op}/I_R versus ambient temperature T_A

(rated temperature T_R = +85 °C)



Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.

  Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application.** As a rule we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified.** In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (www.tdk-electronics.tdk.com/material). Should you have any more detailed questions, please contact our sales offices.
5. We constantly strive to improve our products. Consequently, **the products described in this publication may change from time to time**. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order.

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6. Unless otherwise agreed in individual contracts, **all orders are subject to our General Terms and Conditions of Supply.**
7. **Our manufacturing sites serving the automotive business apply the IATF 16949 standard.** The IATF certifications confirm our compliance with requirements regarding the quality management system in the automotive industry. Referring to customer requirements and customer specific requirements ("CSR") TDK always has and will continue to have the policy of respecting individual agreements. Even if IATF 16949 may appear to support the acceptance of unilateral requirements, we hereby like to emphasize that **only requirements mutually agreed upon can and will be implemented in our Quality Management System.** For clarification purposes we like to point out that obligations from IATF 16949 shall only become legally binding if individually agreed upon.
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